

Application Serial No: 10/584,116
Responsive to the Office Action mailed on: December 31, 2007

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IN THE CLAIMS

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An optical data communication module comprising:
a base board;
a light emitting element;
a light receiving element;
an IC chip; and
a sealing resin package made of a first resin;
wherein the light emitting element, the light receiving element, and the IC chip are mounted on the base board, and are covered by the sealing resin package;
wherein the base board is formed with a recess including a bottom surface and a circumferential an- inner surface, the bottom surface and the circumferential inner surface of the recess being entirely covered by a grounded metal film which is grounded, the recess accommodating the light emitting element.
2. (Original) The optical data communication module according to claim 1, wherein the light emitting element is an infrared rays emitting element, while the light receiving element is an infrared rays receiving element.
3. (Currently Amended) The optical data communication module according to claim 1, wherein a top surface of the metal film is higher than a top of the light emitting element.
4. (Currently Amended) The optical data communication module according to claim 1, wherein the recess is filled with a second resin having an elastic modulus lower than

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that of the first resin package, the second resin covering the light emitting element in contact with the first resin and the grounded metal film.

5. (Currently Amended) The optical data communication module according to claim 1, wherein the recess is an inverted truncated cone having diameter that becomes becoming diametrically smaller as proceeding toward the bottom surface.

6. (New) The optical data communication module according to claim 1, wherein the grounded metal film includes three layers of different materials.

7. (New) The optical data communication module according to claim 6, wherein the three layers of the grounded metal film include a first layer of copper, a second layer of nickel and a third layer of gold.